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Vishay Siliconix

# Automotive N-Channel 200 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY			
V <sub>DS</sub> (V)	200		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0153		
I <sub>D</sub> (A)	95		
Configuration	Single		
Package	TO-263		

### **FEATURES**

- TrenchFET® power MOSFET
- Package with low thermal resistance
- AEC-Q101 qualified
- 100 % R<sub>a</sub> and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



	D
G <b>o</b> —	
N-Channel MOSFET	<b>o</b> s

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	200	V	
Gate-source voltage		V <sub>GS</sub> ± 20		V	
Continuous drain current	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	95		
	T <sub>C</sub> = 125 °C		55		
Continuous source current (diode conduction) <sup>a</sup>		Is	120	Α	
Pulsed drain current <sup>b</sup>		I <sub>DM</sub>	170		
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	64		
Single pulse avalanche energy	L=0.11IIII	E <sub>AS</sub>	205	mJ	
Maximum power dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	375	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	125	VV	
Operating junction and storage temperature r	ange	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount c	$R_{thJA}$	40	°C/W	
Junction-to-case (drain)		$R_{thJC}$	0.4	C/VV	

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq 300 \,\mu\text{s}$ , duty cycle  $\leq 2 \,\%$ .
- c. When mounted on 1" square PCB (FR4 material).



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PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT	
Static					•			
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		200	-	-	V	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.5	3.0	3.5	V	
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 200 V	-	-	1		
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 200 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	ı	-	50	μΑ	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 200 V, T <sub>J</sub> = 175 °C	-	-	600	1	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	40	-	-	Α	
Drain-source on-state resistance <sup>a</sup>		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A	ı	0.0127	0.0153	Ω	
	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}$	I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C	ı	-	0.0310		
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C	1	-	0.0404		
Forward transconductance b	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		-	54	-	S	
Dynamic <sup>b</sup>								
Input capacitance	C <sub>iss</sub>		V <sub>DS</sub> = 25 V, f = 1 MHz	-	3200	4200	pF	
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	1300	1750		
Reverse transfer capacitance	C <sub>rss</sub>			-	80	110		
Total gate charge <sup>c</sup>	$Q_g$		V <sub>DS</sub> = 100 V, I <sub>D</sub> = 9 A	-	55	85	nC	
Gate-source charge <sup>c</sup>	$Q_{gs}$	$V_{GS} = 10 \text{ V}$		-	14	-		
Gate-drain charge <sup>c</sup>	$Q_{gd}$			-	16.5	-		
Gate Resistance	$R_g$	f = 1 MHz		1.35	2.74	4.20	Ω	
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>				17	30	- ns	
Rise time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 100 V, $R_L$ = 11.1 $\Omega$ $I_D \cong$ 9 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		-	8	15		
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			-	39	60		
Fall time <sup>c</sup>	t <sub>f</sub>			-	16	30		
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>							
Pulsed current <sup>a</sup>	I <sub>SM</sub>				-	170	Α	
Forward voltage	V <sub>SD</sub>	I <sub>F</sub> =	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		0.82	1.5	V	
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 10 A, di/dt = 100 A/μs		-	129	260	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>			-	685	1400	nC	
Reverse recovery fall time	t <sub>a</sub>			ı	106	-	ns	
Reverse recovery rise time	t <sub>b</sub>			-	26	-		
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>			-	-11	-	Α	

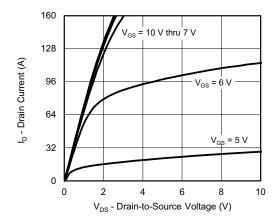
### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

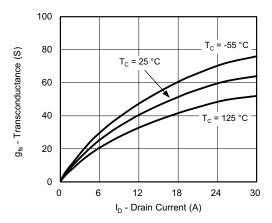
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



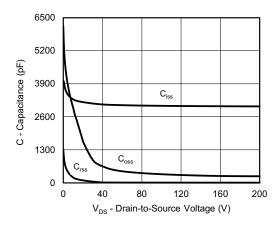
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



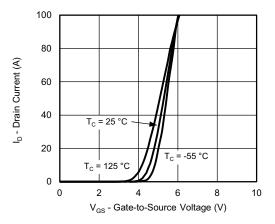
### **Output Characteristics**



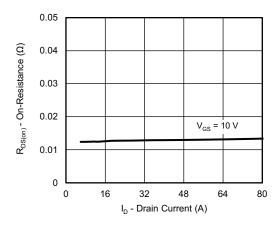
Transconductance



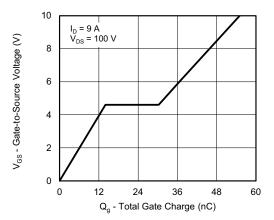
Capacitance



**Transfer Characteristics** 



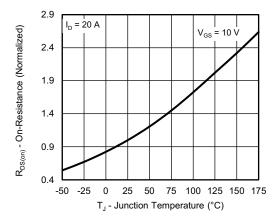
On-Resistance vs. Drain Current



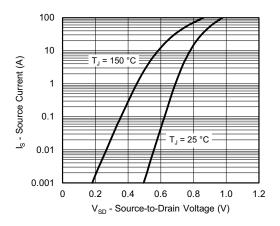
**Gate Charge** 



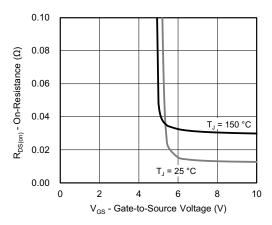
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



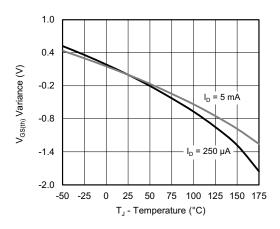
On-Resistance vs. Junction Temperature



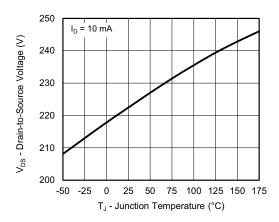
**Source Drain Diode Forward Voltage** 



On-Resistance vs. Gate-to-Source Voltage



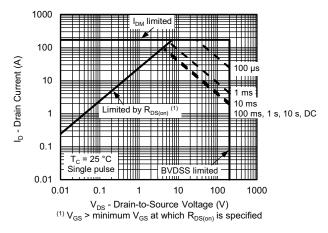
**Threshold Voltage** 



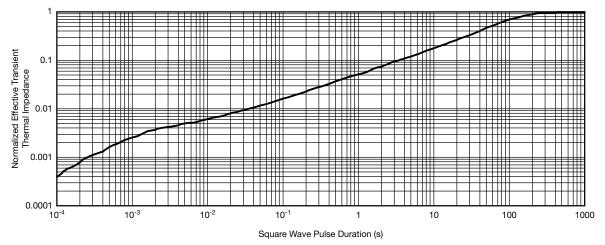
Drain Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



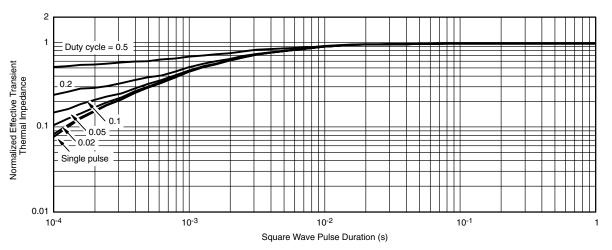
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

can widely vary depending on actual application parameters and operating conditions.

- Normalized Transient Thermal Impedance Junction to Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities

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